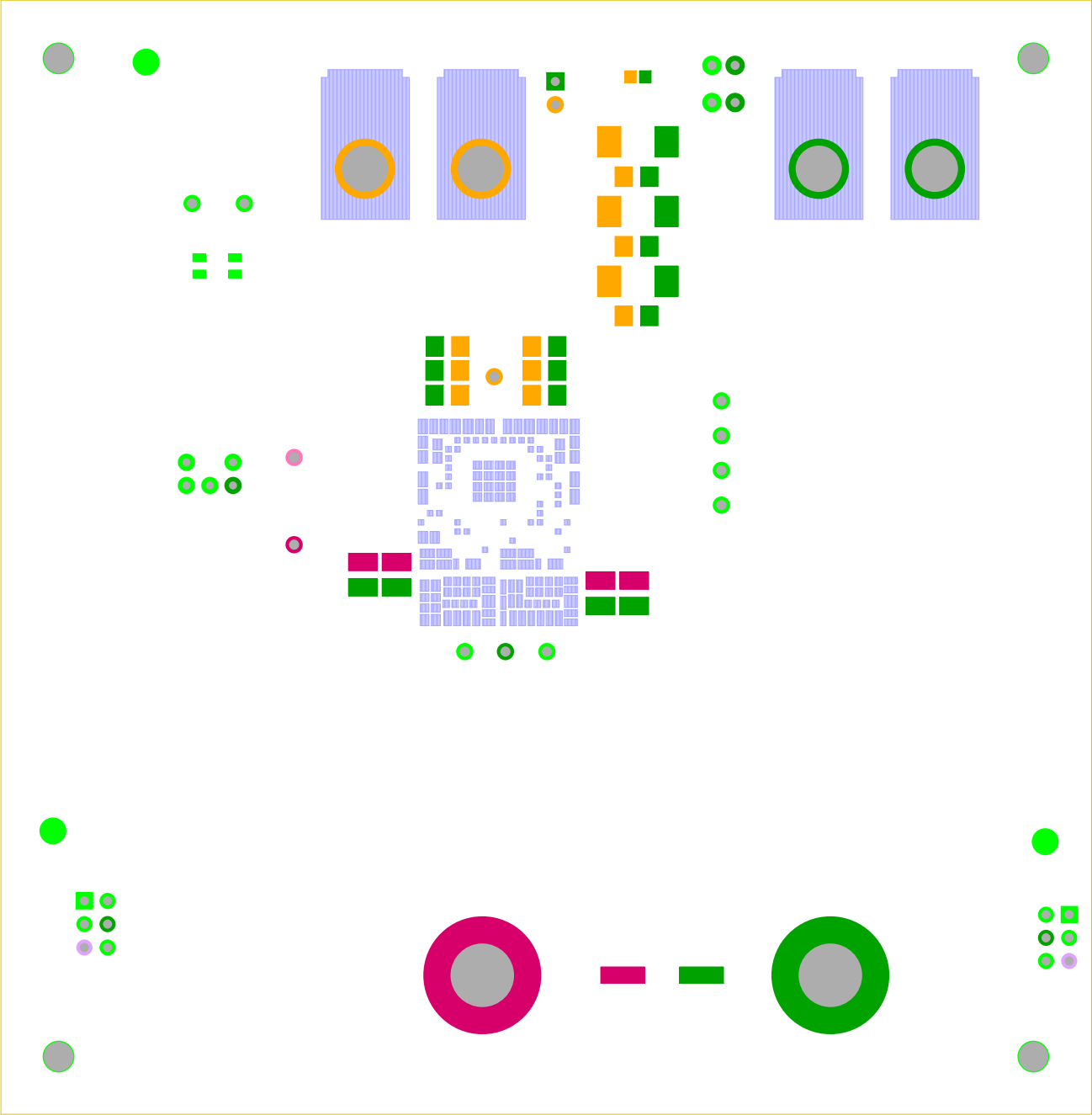
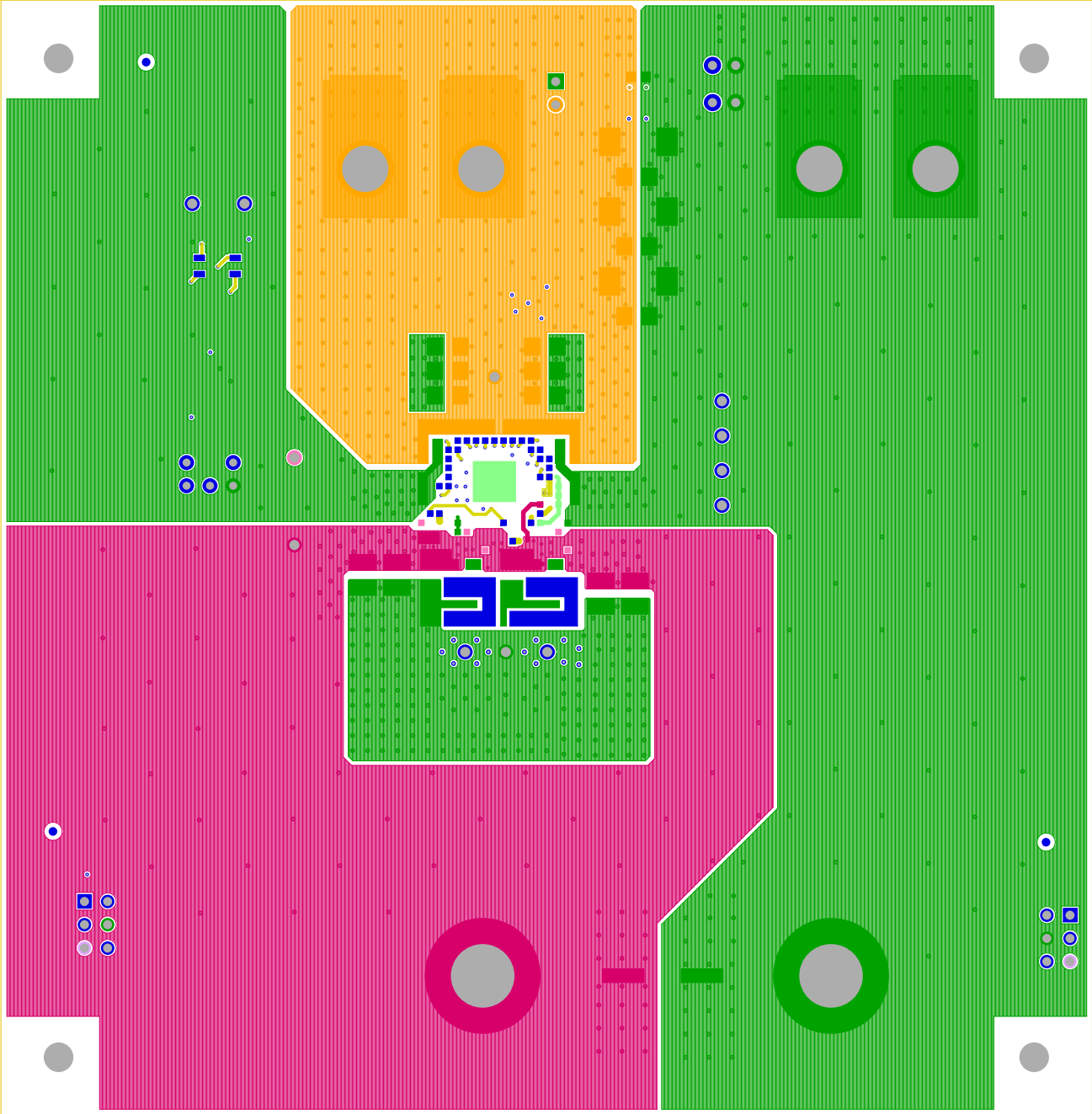
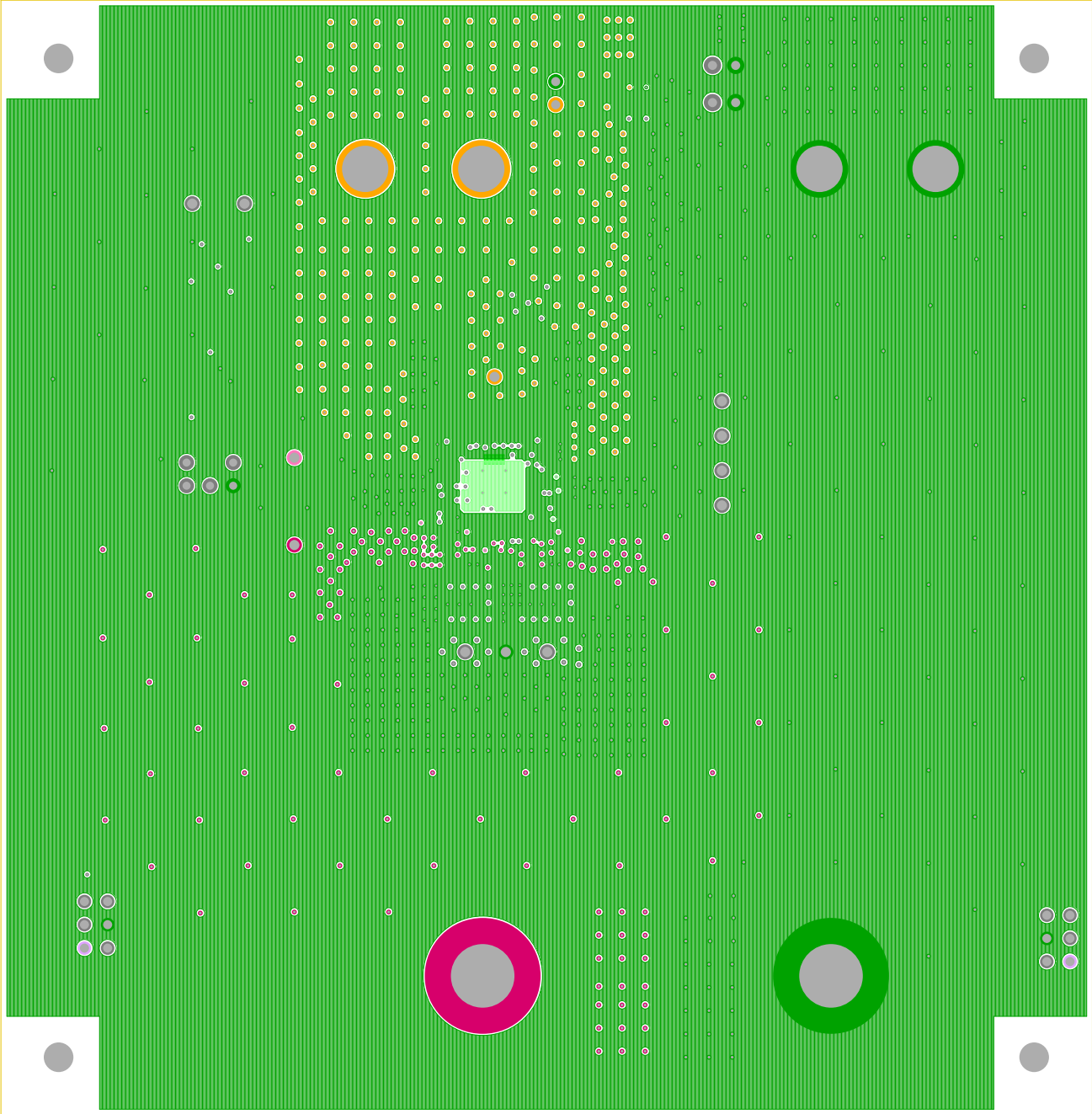


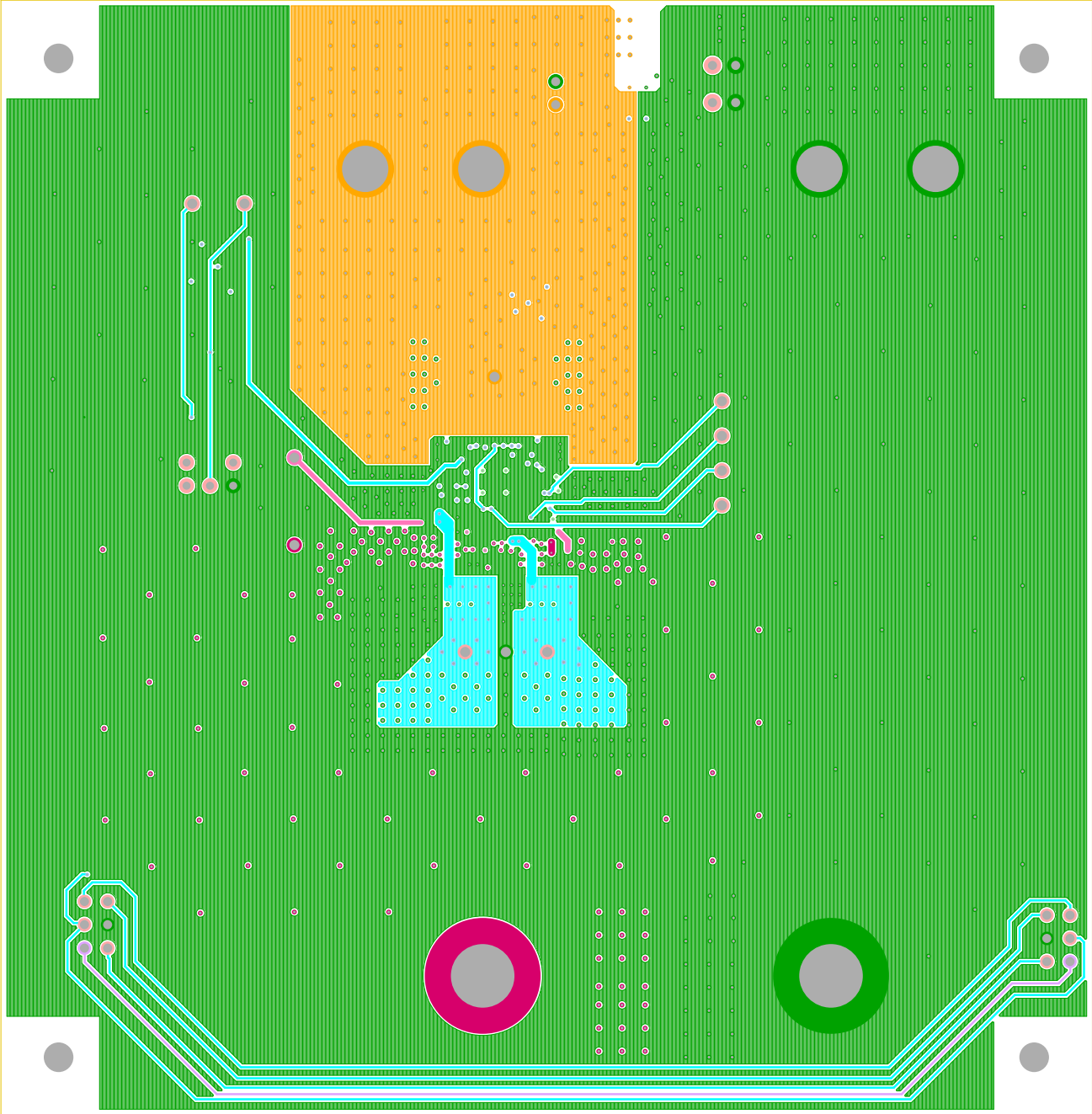
SILK SCREEN TOP
RENESAS CORPORATION
07-26-2018

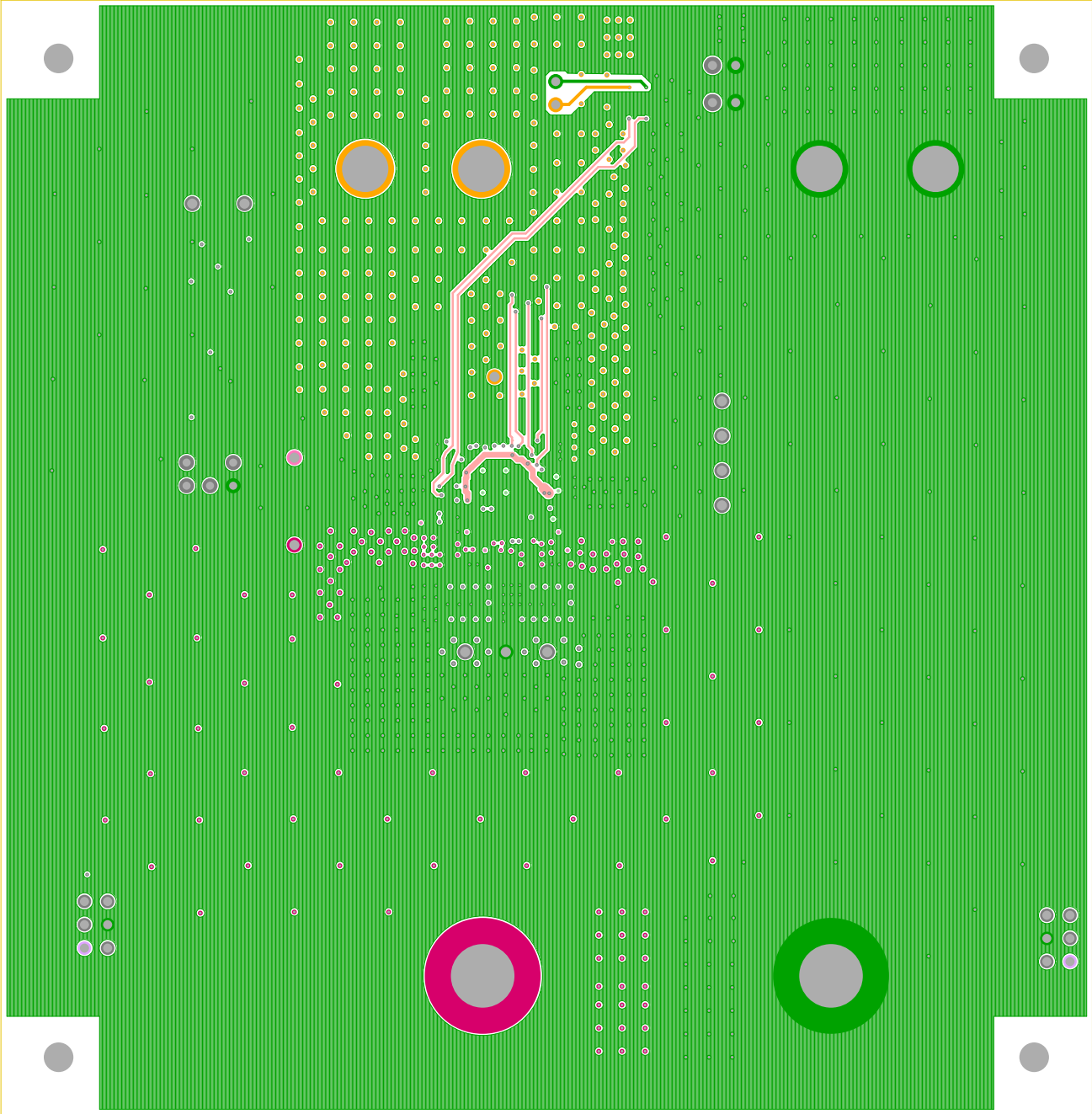


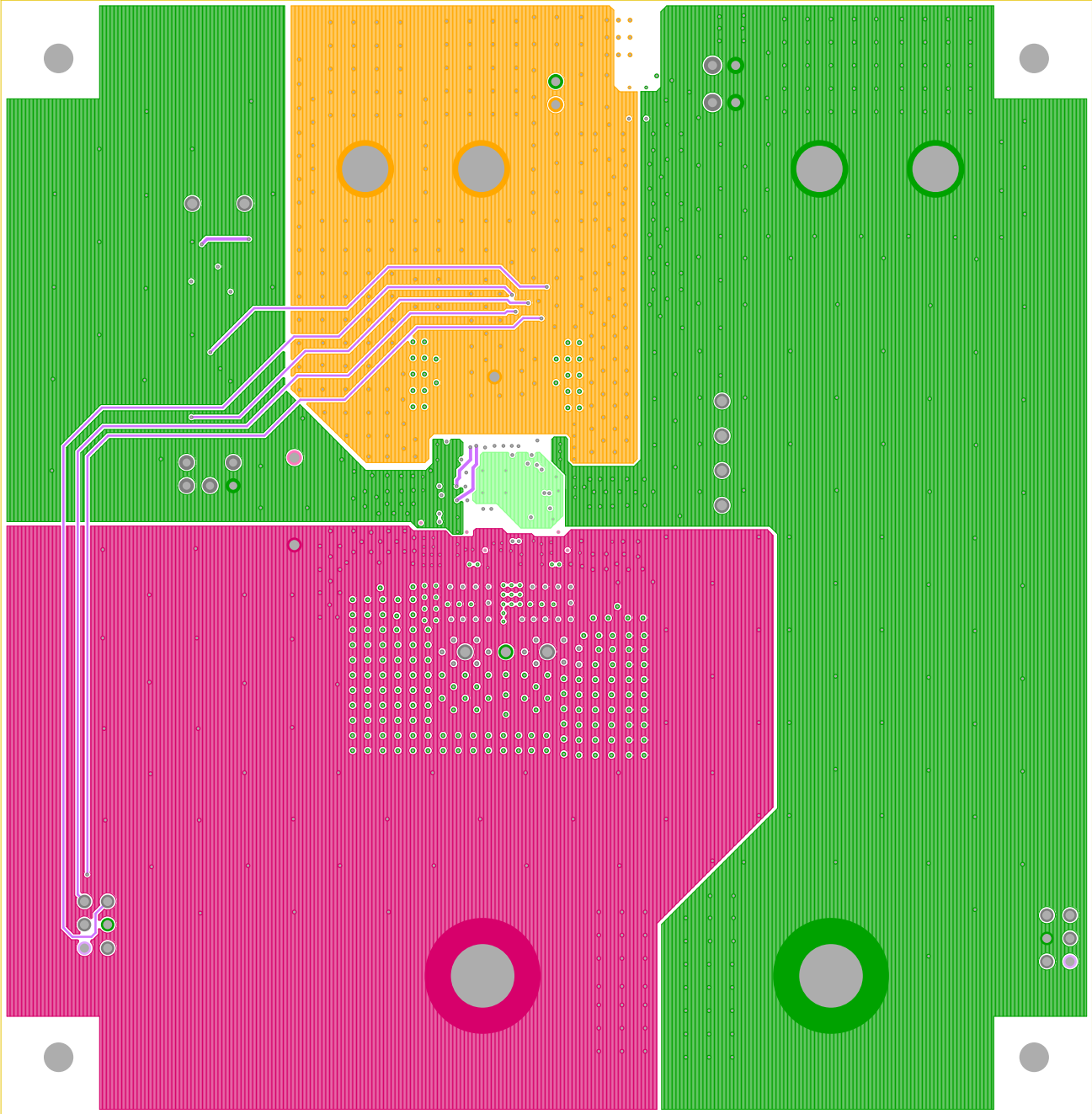
SOLDER MASK TOP
RENESAS CORPORATION
07-26-2018

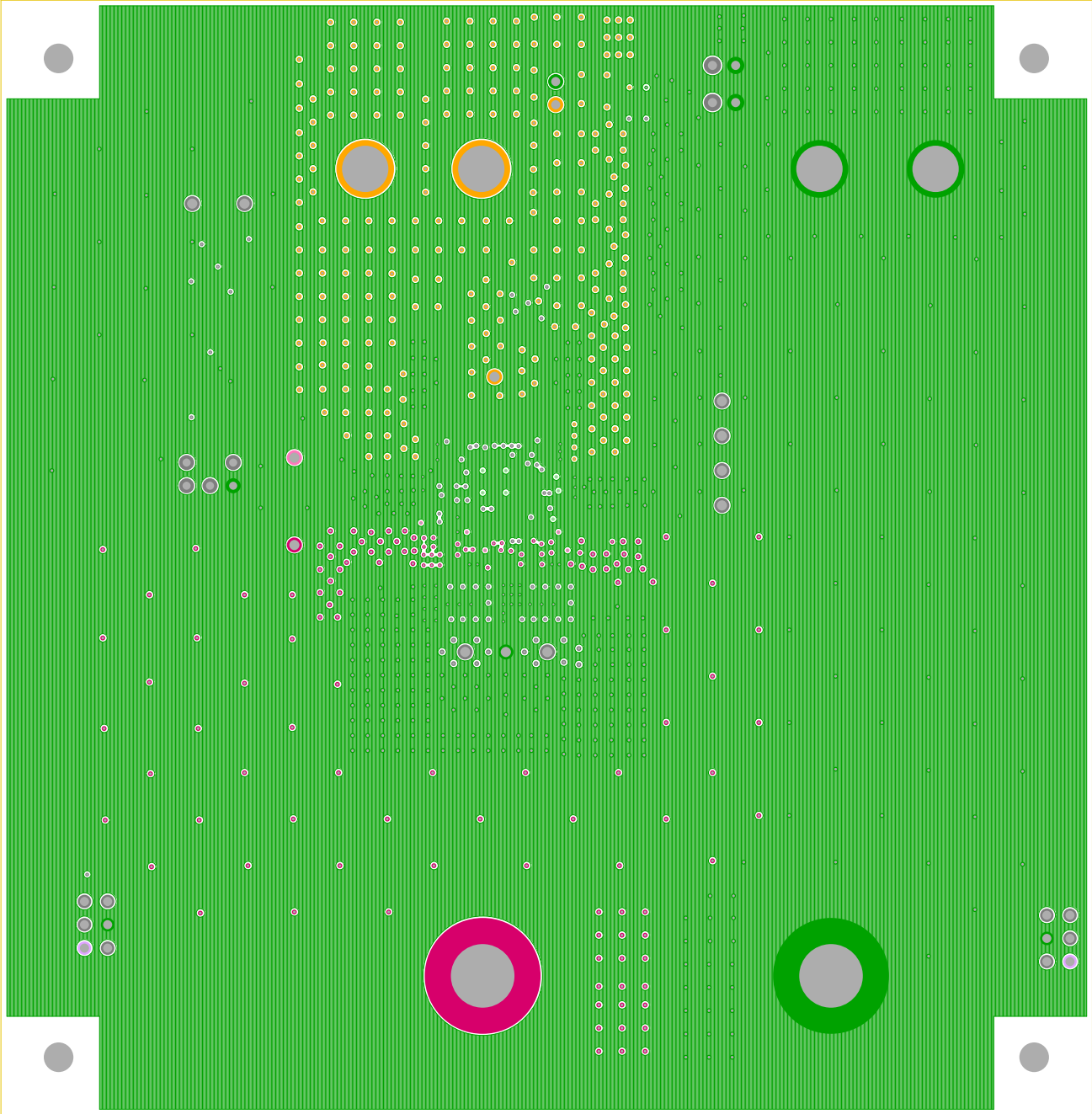


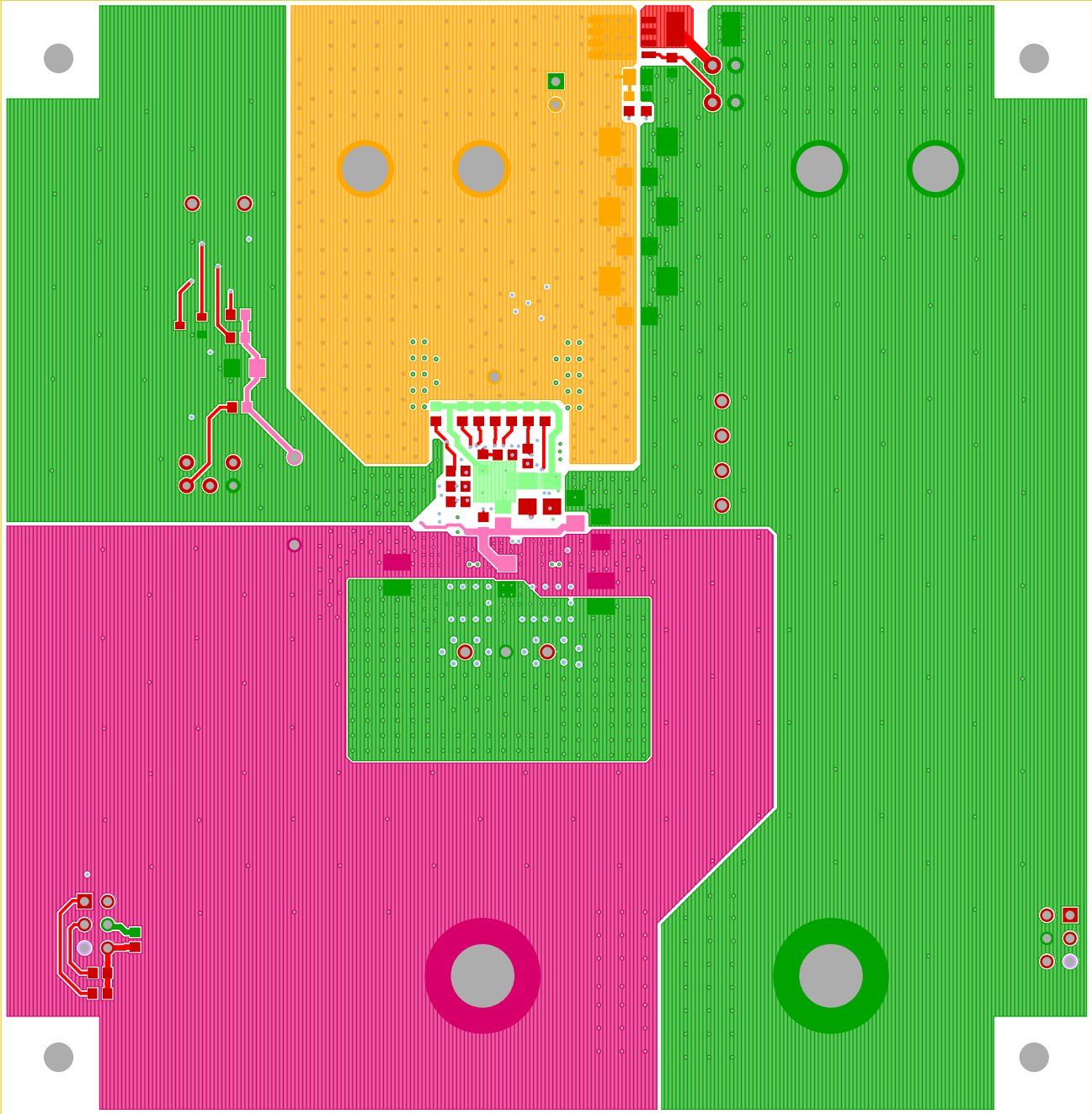








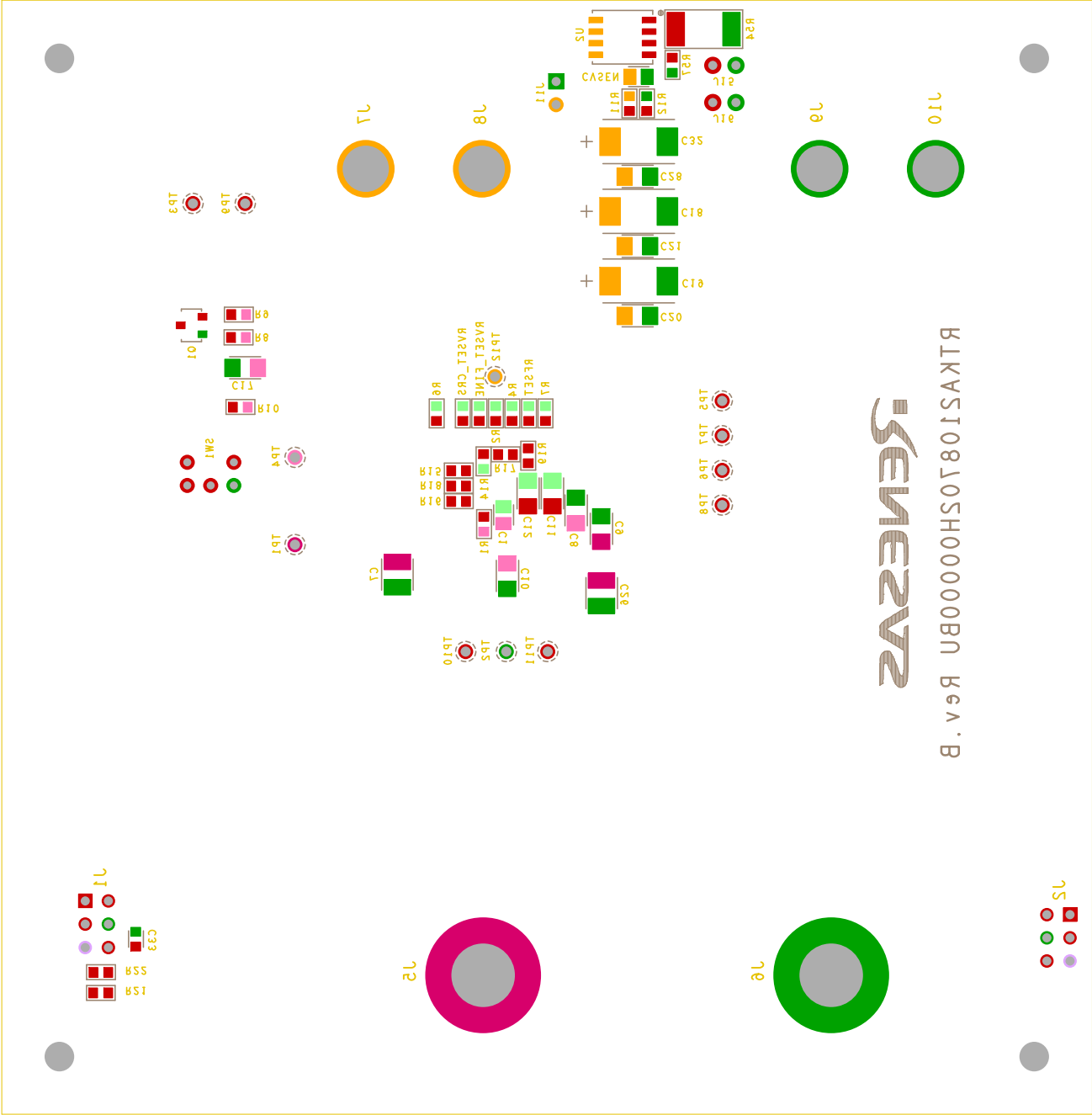




BOTTOM LAYER SOLDER SIDE

RENESAS CORPORATION

07-26-2018



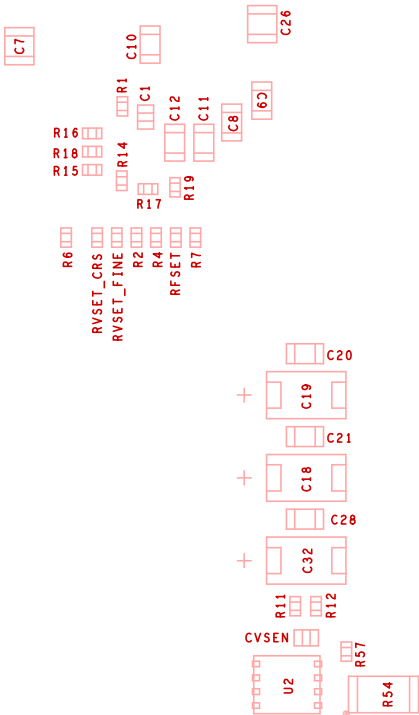
SILK SCREEN BOTTOM
RENESAS CORPORATION
07-26-2018



01-S0-S018
RENEVAS CORPORATION
ASSEMBLY BOTTOM

R21
R22
C33

R10
C17
R8
R9

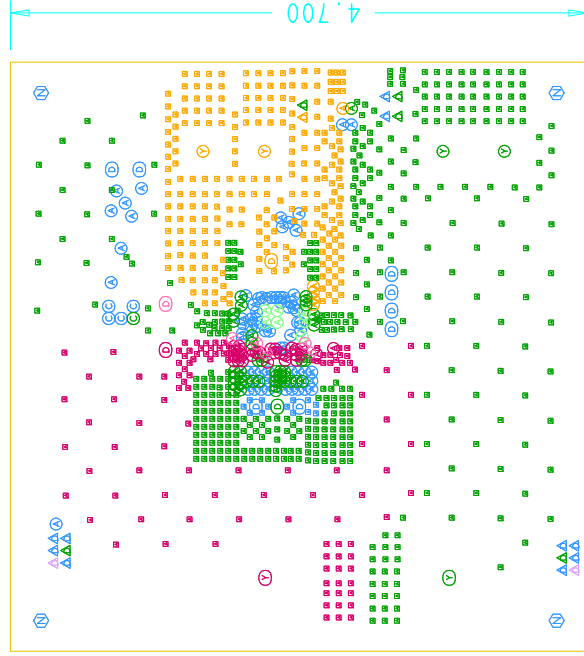


PHYSICAL BOARD DIMENSIONS & LAYER STRUCTURE

	SILK TOP	SILK BOT	SILK TOP	SILK BOT
	MASK TOP	MASK TOP	MASK TOP	MASK TOP
	COMPONENT	COMPONENT	COMPONENT	COMPONENT
	LAYER 2	LAYER 2	LAYER 2	LAYER 2
	LAYER 3	LAYER 3	LAYER 3	LAYER 3
	LAYER 4	LAYER 4	LAYER 4	LAYER 4
	LAYER 5	LAYER 5	LAYER 5	LAYER 5
	LAYER 6	LAYER 6	LAYER 6	LAYER 6
	LAYER 7	LAYER 7	LAYER 7	LAYER 7
	SOLDER	SOLDER	SOLDER	SOLDER
	MASK BOTTOM	MASK BOTTOM	MASK BOTTOM	MASK BOTTOM
	SILK BOTTOM	SILK BOTTOM	SILK BOTTOM	SILK BOTTOM

 $.062^{\circ} \pm 10\%$

4.800



DRILL

Drill Chart: Top to Bottom			
All Units are in MILS			
Figure	Size	Plated	Qty
Ⓐ	10.0	Plated	154
Ⓑ	12.0	Plated	796
Ⓒ	35.0	Plated	5
Ⓓ	41.0	Plated	18
Ⓔ	45.0	Plated	12
Ⓥ	200.0	Plated	4
Ⓦ	275.0	Plated	2
Ⓧ	128.0	Non-Plated	4

NOTES:

1. THIS BOARD IS RoHS COMPLIANT.
2. PRINTED WIRING BOARD DESIGN AND ACCEPTANCE CRITERIA SHALL BE IAW WITH THE REQUIREMENTS OF IPC-D-275 AND IPC-A-600.
3. MATERIAL: FR4 (RoHS COMPLIANT). 2 OZ COPPER.
4. APPLY SOLDER MASK, BOTH SIDES OVER BARE COPPER IAW IPC-SM-840. CLASS 2 (LPI) (BLUE MASK).
5. ALL PATTERNS ARE VIEWED FROM THE PRIMARY SIDE LOOKING THROUGH THE BOARD.
6. UNLESS OTHERWISE SPECIFIED ALL HOLE DIAMETERS ARE AFTER PLATING.
7. APPLY SILKSCREEN USING WHITE NON-CONDUCTIVE EPOXY BASED INK.
8. PWB MUST BE 100% ELECTRICALLY TESTED FOR SHORTS AND CONTINUITY. USE NETLIST PROVIDED RTKAT2108702H000080U-B IPC356. IPC IAW IPC-D-356.
9. MARK DATE CODE AND MANUFACTURES IDENTIFICATION ON SOLDER SIDE PER IPC-6011 AND IPC-6012.
10. TOLERANCE ON ALL DRILL HOLES SHALL BE IAW IPC-D-2221 & 2222 UNLESS OTHERWISE SPECIFIED.
11. NETS GND AND GND_POWER ARE INTENTIONALLY SHORTED ON LAYER 2.
12. ALL 10 MIL VIAS (VIA18C10P) ARE TO BE FILLED WITH CONDUCTIVE MATERIAL AND PLATED OVER (VIMPO)

[illegible]